

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 08/28/2022

Details for "SN65LBC175AN"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN65LBC175AN	NIPDAU	Level-NC-NC-NC	TI AGUASCALIENTES	N 16	6.35x19.3x4.57	1331

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.104077	99.999039	999990	0.007819	78
Precious Metals	Silver	7440-22-4	0.000001	0.000961	10	0	0
Sub-Total			0.104078	100	1000000	0.007819	78
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.49999	78.999967	790000	0.037564	376
Thermoplastics	Epoxy	85954-11-6	0.132909	21.000033	210000	0.009985	100
Sub-Total			0.632899	100	1000000	0.04755	475
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	415.50987	97.05	970500	31.217172	312172
Copper and Its Alloys	Iron	7439-89-6	11.13164	2.6	26000	0.836318	8363
Copper and Its Alloys	Phosphorus	7723-14-0	0.64221	0.15	1500	0.048249	482
Zinc and Its Alloys	Zinc	7440-66-6	0.85628	0.2	2000	0.064332	643
Sub-Total			428.14	100	1000000	32.166071	321661
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	1.417288	95.12	951200	0.106481	1065
Precious Metals	Gold	7440-57-5	0.011622	0.78	7800	0.000873	9
Precious Metals	Palladium	7440-05-3	0.06109	4.1	41000	0.00459	46
Sub-Total			1.49	100	1000000	0.111943	1119
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	790.557948	88	880000	59.394458	593945
Other Plastics and Rubber	Carbon Black	1333-86-4	2.695084	0.3	3000	0.202481	2025
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	4.940987	0.55	5500	0.371215	3712
Thermoplastics	Epoxy	85954-11-6	100.167285	11.15	111500	7.525548	75255
Sub-Total			898.361304	100	1000000	67.493702	674937
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.30154	100	1000000	0.172914	1729
Sub-Total			2.30154	100	1000000	0.172914	1729
Total			1331.029821			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/eoinfo
 Created on: 08/28/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.